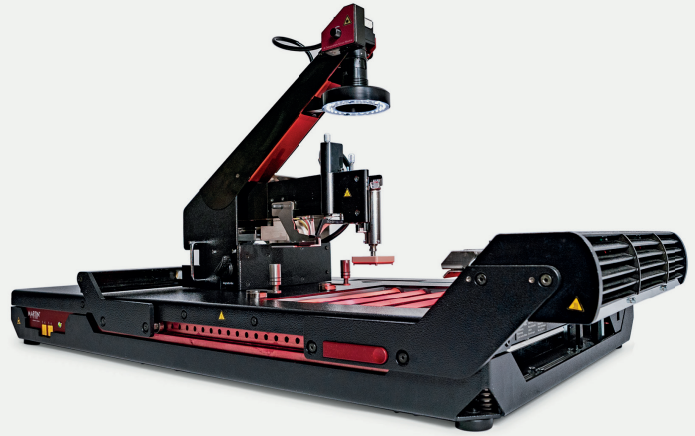


EXPERT 10.6 HV

3,300 W Rework station



Rework Station with 3,300W hybrid under heater. The heating area of 275 x 245 mm² is adjustable to PCB size. Automated SMD placement process by Auto Vision Placer (AVP) incl. EASYSOLDER software package and DBL 06 control unit with six high resolution

sensors inputs for thermocouples (Type K).

This system is particularly suitable for mid-size and large PCBs with fine-pitch components of varying package dimensions.

Top Features

Camera-supported rework



Flexibility

Various PCB sizes and shapes as well as components available



Under-heating system

Highest energy density for thermally demanding boards.



Performance

Uniform heat distribution through convection and hybrid technology



Multifunctionality

One device for all processes, including desoldering, pad cleaning, automatic positioning and soldering



Software

Simple, intuitive, tablet-compatible

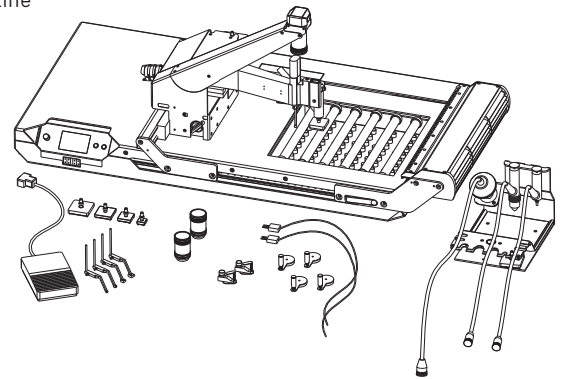


Präzision

Precision of placement within 15 µm

Standard equipment

- Tool set for dispensing, placing, residual solder removal and soldering with magazine
- Set of placement nozzles (BGA/CSP) 3 mm, 5 mm, 8 mm, 10 mm
- Set of solder nozzles (BGA) 15 mm, 27 mm, 35 mm, 40 mm
- Two camera lenses (BGA und CSP)
- Two thermocouple sensors (type K)
- Four PCB magnet holder 40,5 mm (standard)
- Two PCB clips to install at hand rest
- Foot switch
- Rework ABC and manual
- Intuitive software EASYSOLDER 07 with touch integration



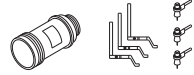

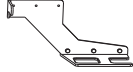
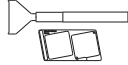
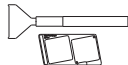

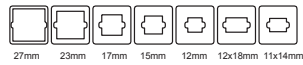
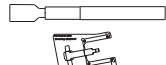


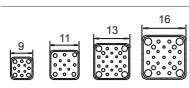
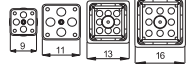
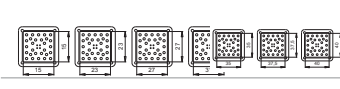
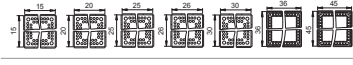




Technical details

Power consumption:	3500 VA	
Power solder pen:	300 W, 35 l/min	
Power under-heating system:	600-3000 W	6 x IR-lamps
Size under-heating system:	275 x 245 mm ²	
Max. PCB size:	305 x 305 mm ²	
Resolution motion system:	0,001 mm	
Placement accuracy:	± 0,015 mm	(Flip Chip)*
	± 0,030 mm	(CSP)
	± 0,040 mm	(BGA)
	± 0,070 mm	(Maxi BGA)*
	± 0,115 mm	(Maxi BGA XL)*

High resolution CMOS-camera:	5 Mio. Pixel USB2	
Camera field of view (FOV):	14 x 18 mm ²	(Flip Chip)*
	28 x 37 mm ²	(CSP)
	37 x 50 mm ²	(BGA)
	65 x 85 mm ²	(Maxi BGA)*
	115 x 160 mm ²	(Maxi BGA XL)*
Mains:	1Phase, 230VAC, Fuse 16A	Connector Type CEE 32A (3 phase)
Pressurized air:	5-8 bar, 100 l/min,	clean, dry air
Dimensions:	865 x 460 mm ²	

* Optional extras

EXPERT 10.6 HV: Optional extras

	Article nr.	Name
	SF66.0004	Micro SMD nozzles and lens for AVP 4 licence MS, 3 n, 3 solder n, lens FC
	SF71.0003	IR temperatur sensor for AVP04.1
	SF64.0501	Tool slider for AVP 4.1
	SF64.0525	Dipp tool 32x0,08mm with squeegee for tool slider
	SF64.0526	Dipp tool 32x0,15mm with squeegee for tool slider
	SF64.0527	Dipp tool 32x0,22mm with squeegee for tool slider
	AT10.0100	Chip Frame Set Dipp Tool 7 pcs (11x14,12x18,12,15,17,23,27)
	SF64.0520	Print tool with squeegee for tool slider
	SF64.0540	µSMD tool for tool slider
	SF66.0110	Lens Maxi BGA XL for AVP4/4XL, f=16mm, 65*85mm
	LW40.1096	Soldering nozzle set CSP/QFN for all CSP types, 4 pieces (9, 11, 13, 16)
	LW40.1104	Soldering nozzle set CSP with vacuum for all CSP types, 4 pieces (9, 11, 13, 16)
	LW40.1099	Solder Nozzle Set BGA 7 for all (98%) types of BGA, 7 pieces
	LW01.0100	Soldering Tool Set QFP for all PLCC ...QFP, 7 pieces
	SF36.1001	PCB flex support 40,5 for HIF 08 and IRF, "10 pin"
	SF71.0004	Side Camera (lens 35mm) for ES 05, camera, stand, cable, DVD
	SF71.0007	Lens Side Camera f=16mm
	DB00.0025	Nitrogen input for DBL 04/05/06(2.p.r) reduces consumption of N2 for vacuum

More accessories and consumables at www.martin-smt.de